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(54) Title: POLISHING PAD WITH ORIENTED PORE STRUCTURE



(57) Abstract: The invention provides a polishing pad for chemical-mechanical polishing comprising a body, a polishing surface, and a plurality of elongated pores, wherein 10% or more of the elongated pores have an aspect ratio of 2:1 or greater and are substantially oriented in a direction that is coplanar with the polishing surface. The invention further provides a method of polishing a substrate.

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— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations*

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